

CL10-7258

Buried Electrode

Description

CL10-7258 is a pure palladium buried electrode. It fires to a dense internal layer, without mismatch, to a variety of high fire body types. Titanate based ceramic has been added to the formulation to match the thermal expansion rates between the ceramic tape and the metal electrode. CL10-7258 is supplied with a clean burnout organic system, specifically formulated to reduce vertical delaminations.

Key Features

- Low ESR For high frequency parts Compatible with acrylic and PVB based dielectric tapes



This picture does not show the packaging of CL10-7258 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	21-31 Kcps, Brookfield RVT, SC4-14 spindle and 6R utility cup @ 10 rpm, 25°C.
Solids	57.5 ± 1%
Alloy Ratio	100
Metal	Pd

Recommended Processing Guide

Printing Parameters	325 stainless steel mesh screen 0.5 mil emulsion 1.1 mil wire.
Drying Temperature	120-150°C for 5 minutes
Process Temperature (TDS)	1450°C maximum peak temperature
Recommended Thinner	RV-150

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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